

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Takayuki HASHIMOTO</td> <td>08/07/2009</td> </tr> <tr> <td>Takashi HIRAO</td> <td>08/10/2009</td> </tr> <tr> <td>Noboru AKIYAMA</td> <td>08/20/2009</td> </tr> </tbody> </table>		Name	Execution Date	Takayuki HASHIMOTO	08/07/2009	Takashi HIRAO	08/10/2009	Noboru AKIYAMA	08/20/2009
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Takayuki HASHIMOTO	08/07/2009								
Takashi HIRAO	08/10/2009								
Noboru AKIYAMA	08/20/2009								
RECEIVING PARTY DATA									
Name:	RENESAS TECHNOLOGY CORP.								
Street Address:	6-2, Otemachi 2-chome								
City:	Chiyoda-ku, Tokyo								
State/Country:	JAPAN								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12483668</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12483668				
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Application Number:	12483668								
CORRESPONDENCE DATA									
Fax Number:	(703)684-1460								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
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NAME OF SUBMITTER:	Daniel J. Stanger								
Total Attachments: 1 source=1014-Assignment#page1.tif									

OP \$40.00 12483668

ASSIGNMENT
(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Renesas Technology Corp., a corporation organized under the laws of Japan, located at 6-2, Otemachi 2-chome, Chiyoda-Ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Renesas Technology Corp., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

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invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Renesas Technology Corp., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Renesas Technology Corp.,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>Takayuki Hashimoto</u> (Takayuki HASHIMOTO)	<u>8/7/2009</u>
2) <u>Takashi Hiraio</u> (Takashi HIRAO)	<u>8/10/2009</u>
3) <u>Noboru Akiyama</u> (Noboru AKIYAMA)	<u>8/20/2009</u>
4) _____	_____
5) _____	_____
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____